

- **EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **Member of the Texas Instruments Widebus™ Family**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Options Include Plastic 300-Mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages**

description

This 16-bit buffer/driver is designed for 2.3-V to 3.6-V V_{CC} operation.

The SN74ALVCH16541 is a noninverting 16-bit buffer composed of two 8-bit sections with separate output-enable signals. For either 8-bit buffer section, the output enables ($1\overline{OE}1$ and $1\overline{OE}2$ or $2\overline{OE}1$ and $2\overline{OE}2$) must both be low for the corresponding Y outputs to be active. If either output-enable input is high, the outputs of that 8-bit buffer section are in the high-impedance state.

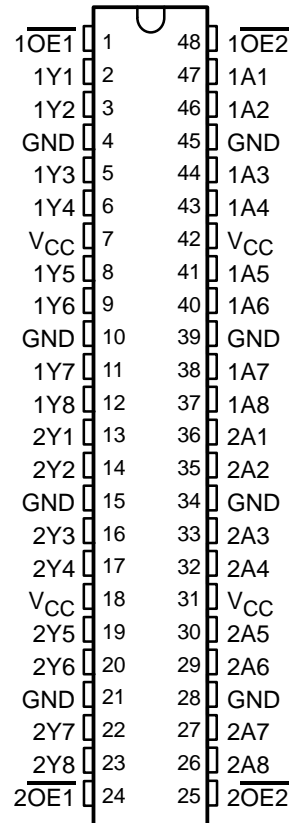
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16541 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVCH16541 is characterized for operation from -40°C to 85°C .

DGG OR DL PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 8-bit section)

INPUTS			OUTPUT Y
$\overline{OE}1$	$\overline{OE}2$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z



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PRODUCT PREVIEW

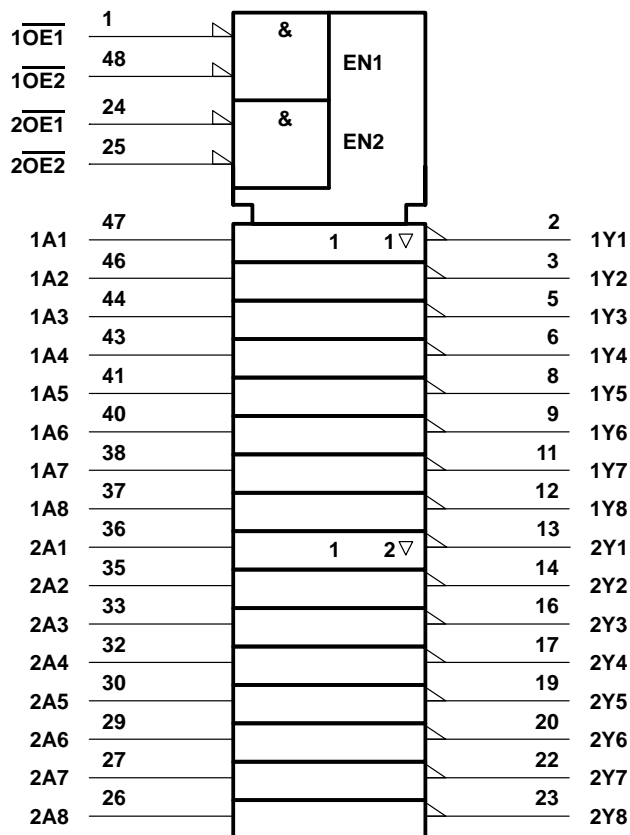
SN74ALVCH16541

16-BIT BUFFER/DRIVER

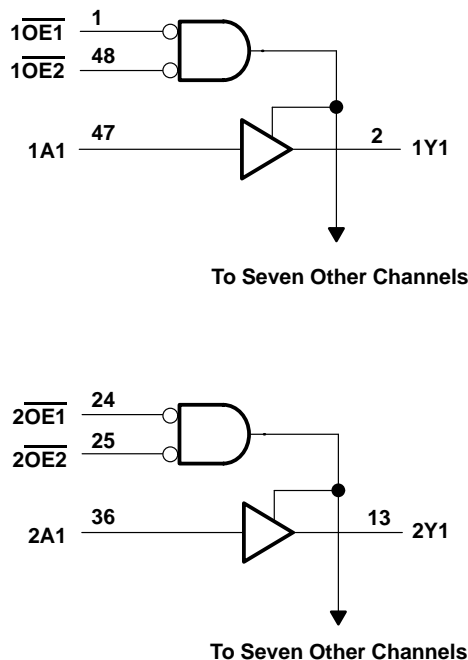
WITH 3-STATE OUTPUTS

SCES031 – JULY 1995

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I : (see Note 1)	–0.5 V to 4.6 V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This value is limited to 4.6 V maximum.
 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2.3 \text{ V}$		-12	mA
		$V_{CC} = 2.7 \text{ V}$		-12	
		$V_{CC} = 3 \text{ V}$		-24	
I_{OL}	Low-level output current	$V_{CC} = 2.3 \text{ V}$		12	mA
		$V_{CC} = 2.7 \text{ V}$		12	
		$V_{CC} = 3 \text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0	10	ns/V
T_A	Operating free-air temperature		-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

PRODUCT PREVIEW

SN74ALVCH16541
16-BIT BUFFER/DRIVER
WITH 3-STATE OUTPUTS

SCES031 – JULY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC} [†]	MIN	TYP [‡]	MAX	UNIT
V _{OH}	I _{OH} = –100 µA	MIN to MAX	V _{CC} – 0.2			V
	I _{OH} = –6 mA, V _{IH} = 1.7 V	2.3 V	2			
	I _{OH} = –12 mA	V _{IH} = 1.7 V	2.3 V		1.7	
		V _{IH} = 2 V	2.7 V		2.2	
		V _{IH} = 2 V	3 V		2.4	
	I _{OH} = –24 mA, V _{IH} = 2 V	3 V	2			
V _{OL}	I _{OL} = 100 µA	MIN to MAX			0.2	V
	I _{OL} = 6 mA, V _{IL} = 0.7 V	2.3 V			0.4	
	I _{OL} = 12 mA	V _{IL} = 0.7 V	2.3 V		0.7	
		V _{IL} = 0.8 V	2.7 V		0.4	
	I _{OL} = 24 mA, V _{IL} = 0.8 V	3 V			0.55	
I _I	V _I = V _{CC} or GND	3.6 V			±5	µA
I _{I(hold)}	V _I = 0.7 V	2.3 V	45			µA
	V _I = 1.7 V		–45			
	V _I = 0.8 V	3 V	75			
	V _I = 2 V		–75			
	V _I = 0 to 3.6 V	3.6 V			±500	
I _{OZ}	V _O = V _{CC} or GND	3.6 V			±10	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V			40	µA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	µA
C _i	V _I = V _{CC} or GND	3.3 V				pF
C _o	V _O = V _{CC} or GND	3.3 V				pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] All typical values are at V_{CC} = 3.3 V.

[§] For I/O ports, the parameter I_{OZ} includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figures 1 and 2)

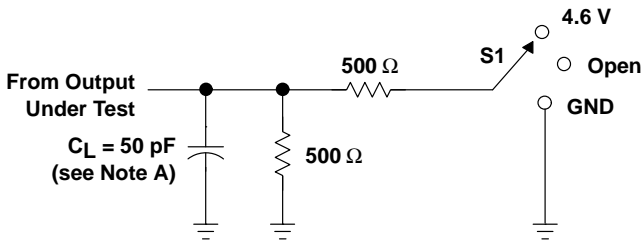
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y							ns
t _{en}	$\overline{\text{OE}}$	Y							ns
t _{dis}	$\overline{\text{OE}}$	Y							ns

operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	
C _{pd}	Power dissipation capacitance	Outputs enabled	C _L = 50 pF, f = 10 MHz			pF
		Outputs disabled				

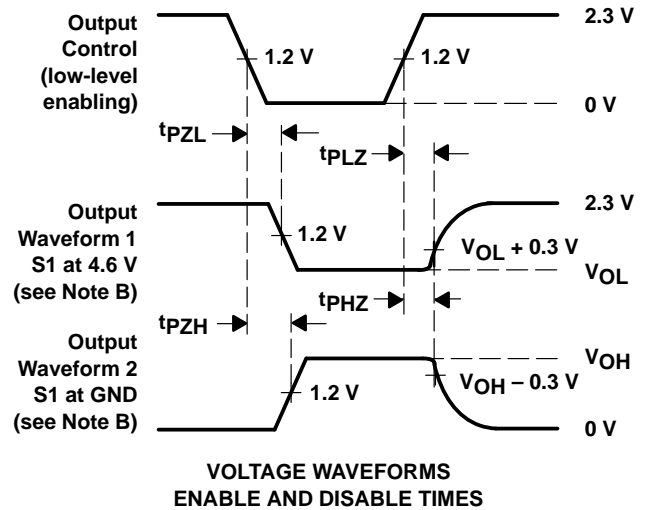
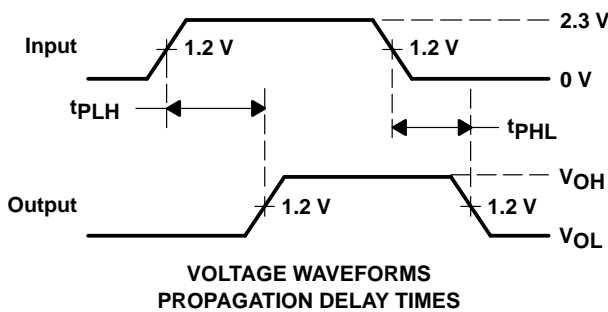
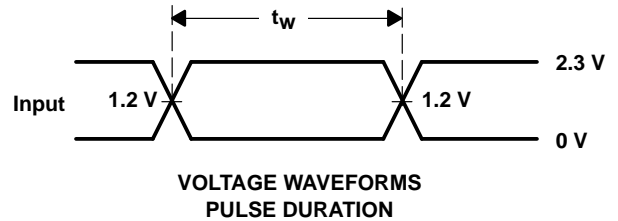
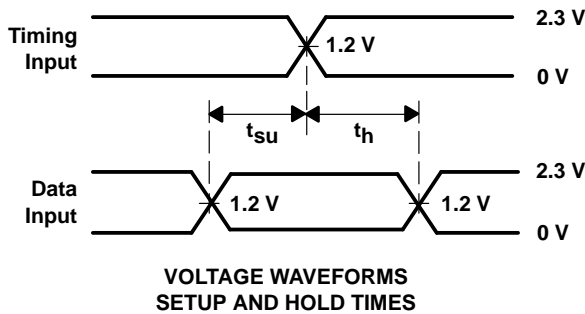


PARAMETER MEASUREMENT INFORMATION
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$



LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	4.6 V
t_{PHZ}/t_{PZH}	GND



- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

SN74ALVCH16541

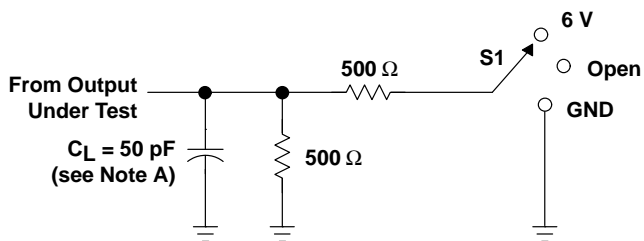
16-BIT BUFFER/DRIVER

WITH 3-STATE OUTPUTS

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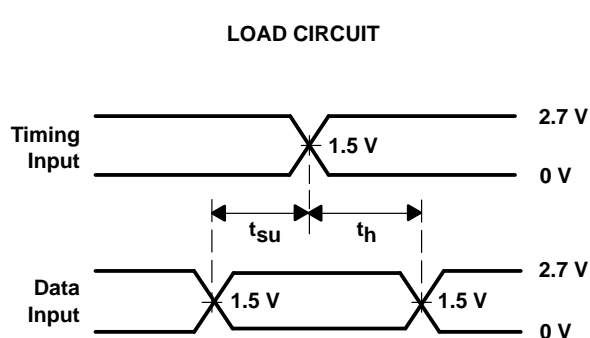
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V AND } 3.3\text{ V} \pm 0.3\text{ V}$

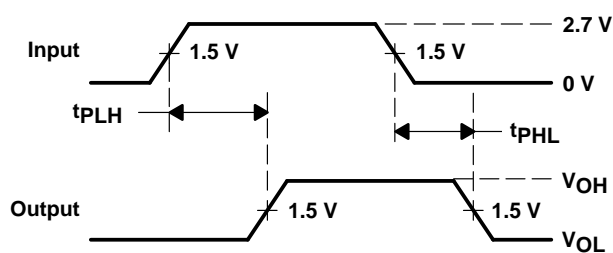


LOAD CIRCUIT

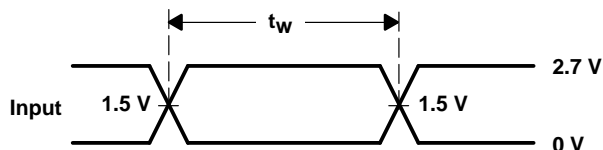
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



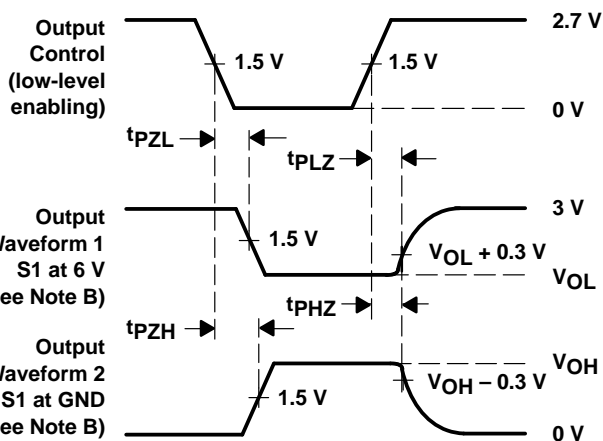
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

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